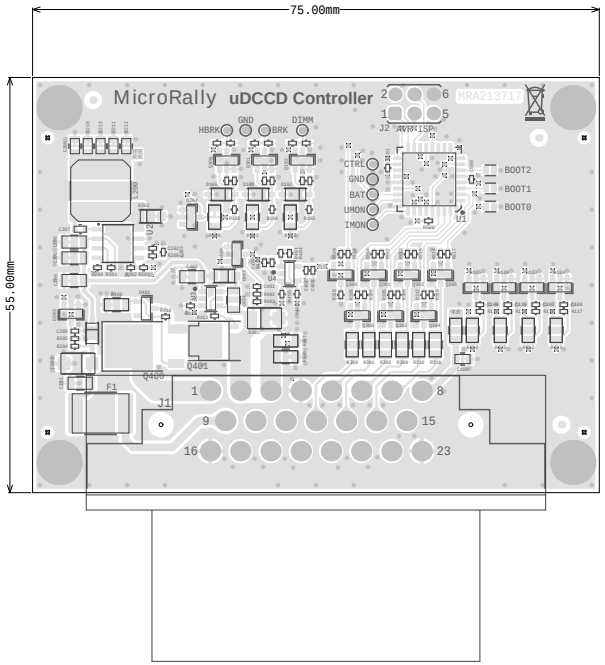
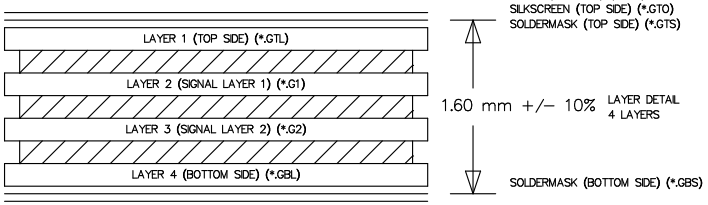
GERBER NOTES



Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⊠	337	0.300mm	PTH	Round	Via
⌬	9	0.500mm	PTH	Round	Pad
✡	6	1.000mm	PTH	Round	Pad
⊠	4	1.152mm	NPTH	Round	Pad
□	23	1.600mm	PTH	Round	Pad
○	2	2.850mm	NPTH	Round	Pad
▽	4	3.600mm	PTH	Round	Pad
	385 Total				

1.0 OZ L1
0.20 mm Pregreg – FR4
0.5 OZ L2
1.065 mm Core – FR4
0.5 OZ L3
0.20 mm Pregreg – FR4
1.0 OZ L4

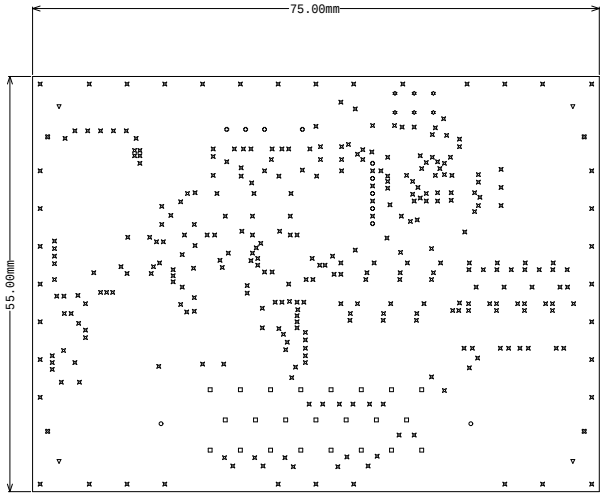


NOTES: (UNLESS OTHERWISE SPECIFIED)

1) THIS IS 4 LAYER BOARD
2) MATERIAL: FR4, TG 150 DEGREE C MIN
3) FR4 DIELECTRIC CONSTANT NOT SPECIFIED
4) FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
5) TRACE WIDTHS IN ARTWORK ARE FINISHED SIZES
6) SEE FILM FOR LAYER SEQUENCE AND COPPER THICKNESSES (SHOWN BEFORE PLATING)
7) MIN TRACE/SPACE 0.20/0.20MM
8) SEE DRILL CHART FOR FINISHED HOLE SIZES
9) MIN DRILL 0.30MM
10) HOLE TOLERANCE IS +/-3MIL UNLESS OTHERWISE SPECIFIED
    HOLE COPPER THICKNESS MIN 0.7MIL
    SLOT TOLERANCE +/-0.1MM
    BORDER OUTLINE TOLERANCE +/-0.15MM
11) SURFACE PLATING: HASL, Pb FREE
12) SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
13) SILKSCREEN: TOP SIDE. COLOR WHITE
14) ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUNITY (OPENS)

Project: uDCCD Controller	
Author: Andis Jargans	Revision: 7
Date: 15.09.2021	Size: A4
File: uDCCD_controller_r7.PcbDoc	MicroRally

GERBER NOTES



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⊠	337	0.300mm	PTH	Round	Via
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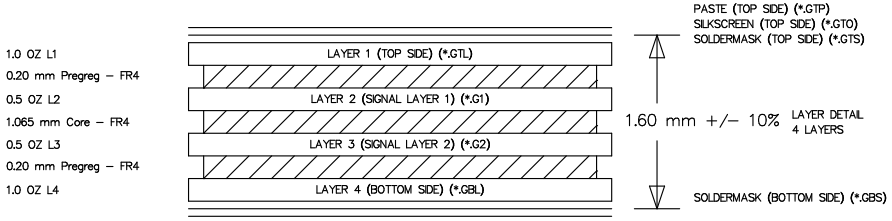
▽	4	3.600mm	PTH	Round	Pad
	385 Total				



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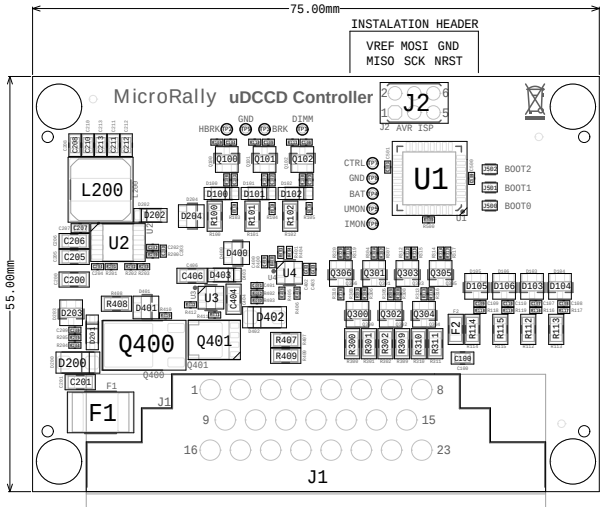
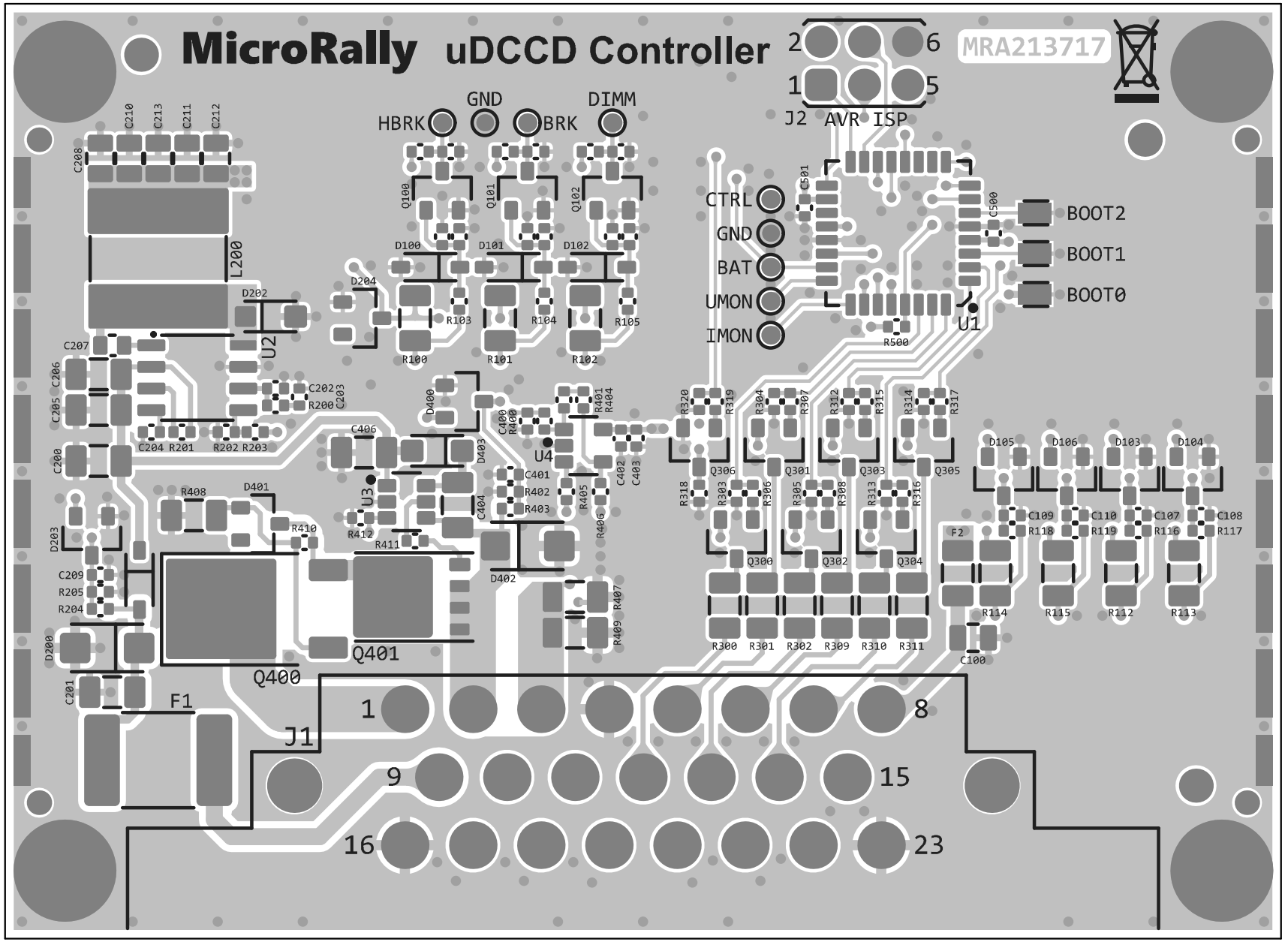
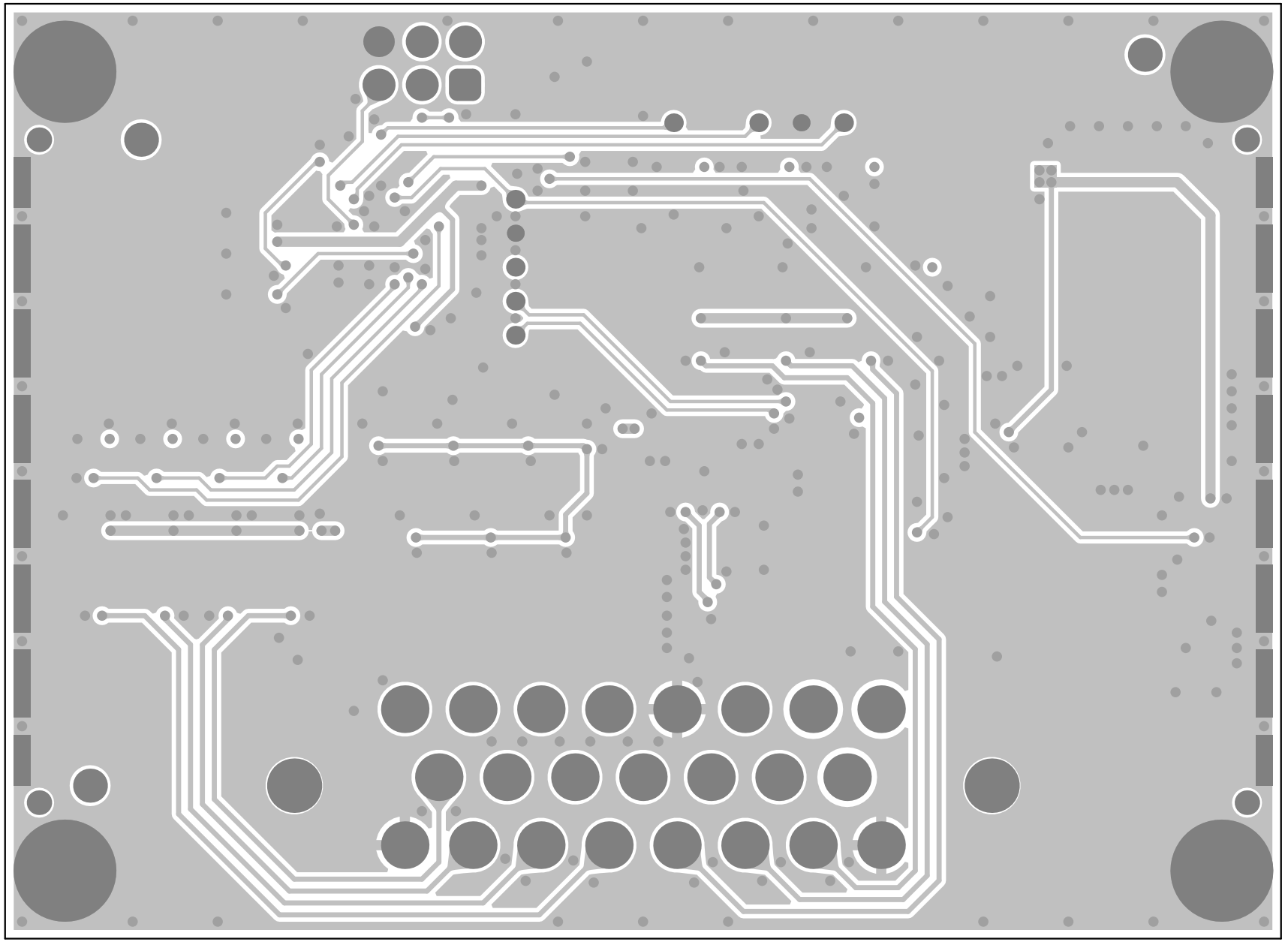
Project: uDCCD Controller	
Author: Andis Jargans	Revision: 7
Date: 15.09.2021	Size: A4
File: uDCCD_controller_r7.PcbDoc	MicroRally

ASSEMBLY NOTES



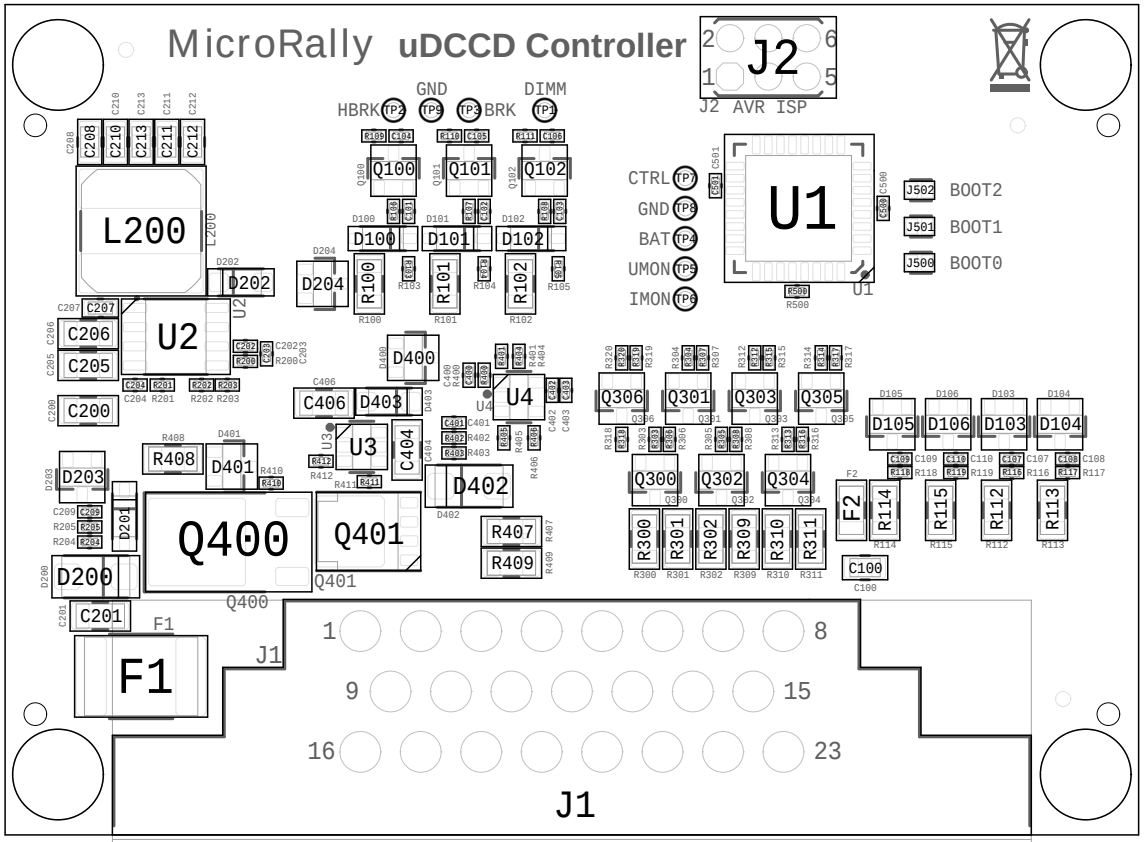
Project: uDCCD Controller	
Author: Andis Jargans	Revision: 7
Date: 15.09.2021	Size: A4
File: uDCCD_controller_r7.PcbDoc	MicroRally


MicroRally uDCCD Controller
MRA213717
HBRK
GND
BRK
DIMM
J2 AVR ISP
CTRL
GND
BAT
UMON
IMON
BOOT2
BOOT1
BOOT0
U1
U2
U3
U4
Q400
Q401
F1
F2
J1
1
8
9
15
16
23



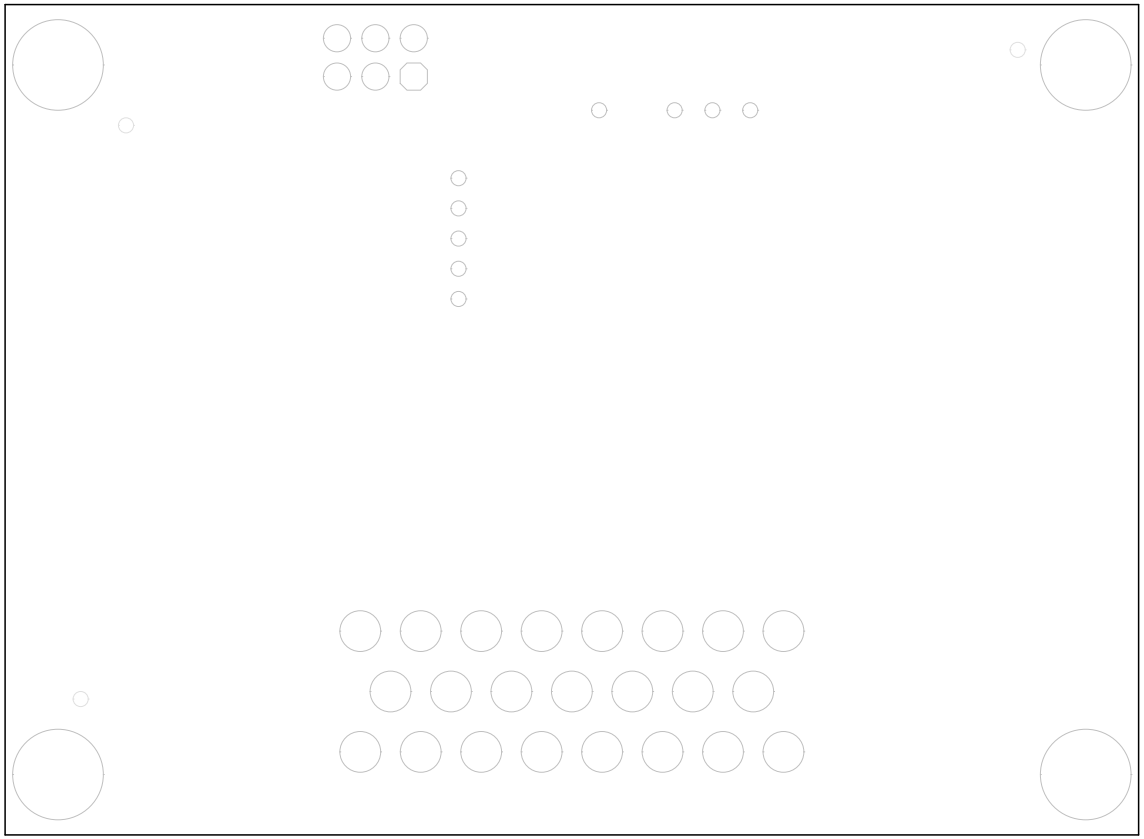
INSTALATION HEADER

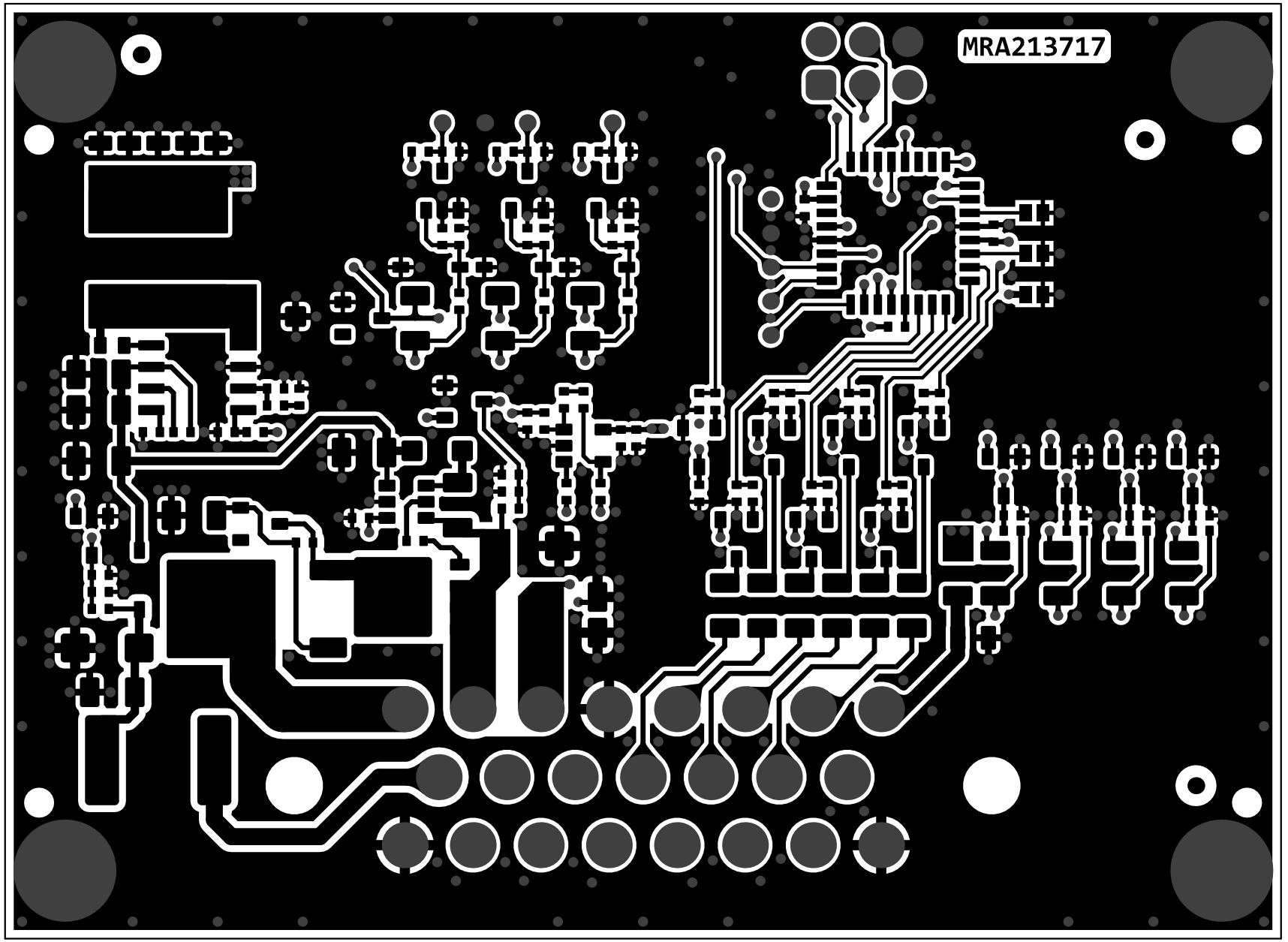
VREF	MOSI	GND
MISO	SCK	NRST

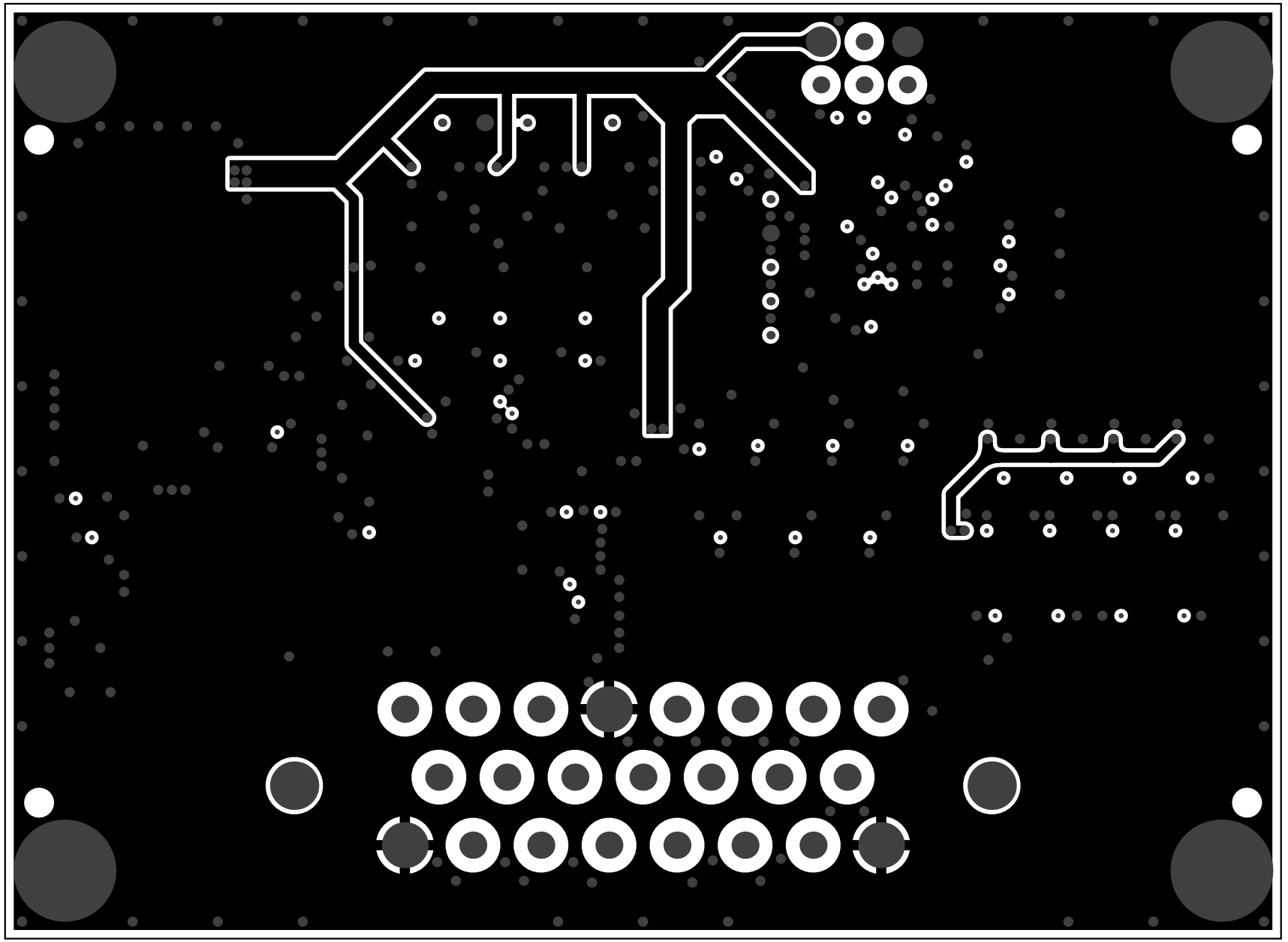


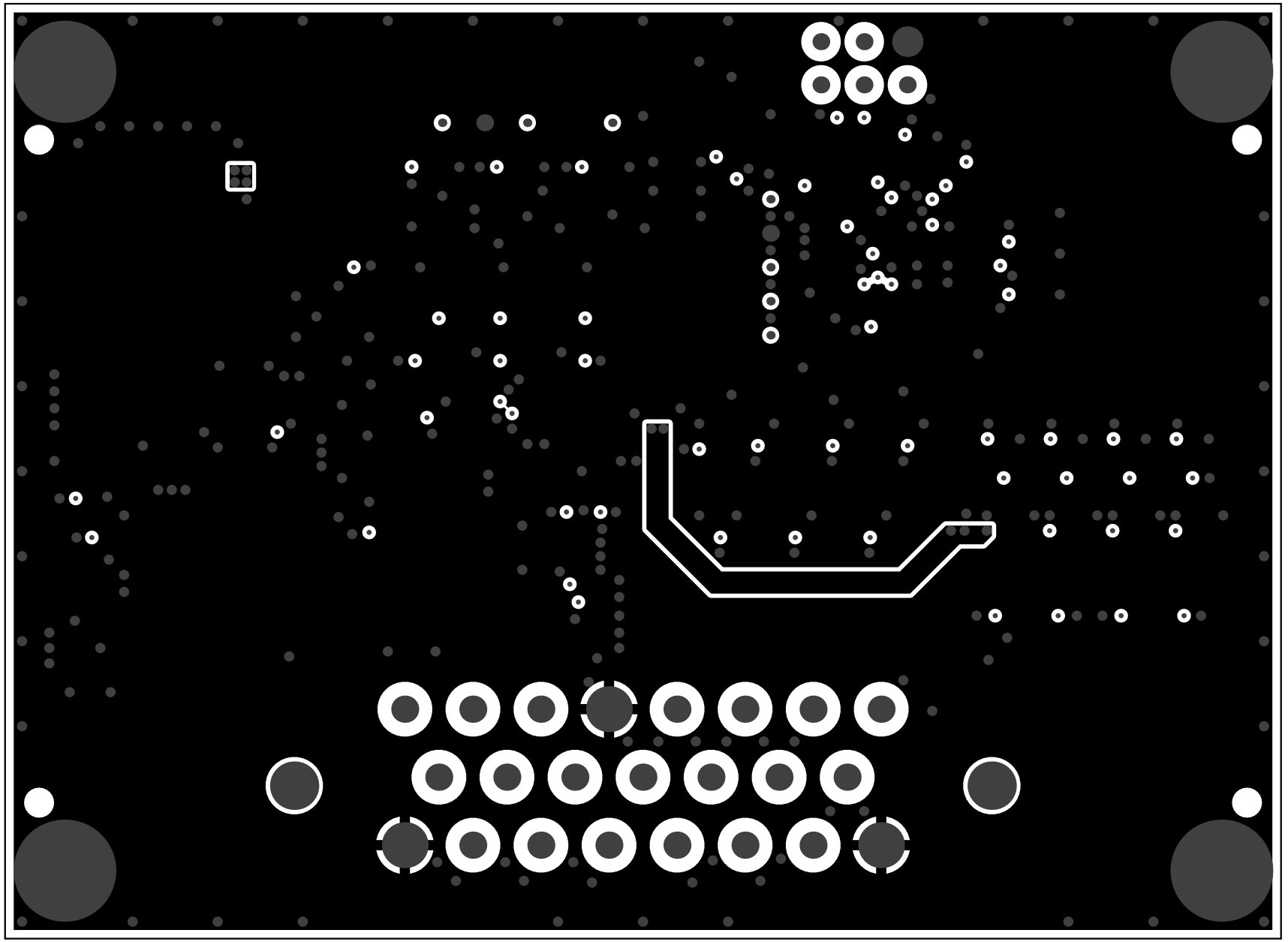
VBAT	DCCD+	DCCD-	PGND	LED1	LED3	LED5	5V
VIGN	N.C.	N.C.	LED0	LED2	LED4	UP	
GND	DIMM	BRK	HBRK	MODE	POT	DOWN	IGND

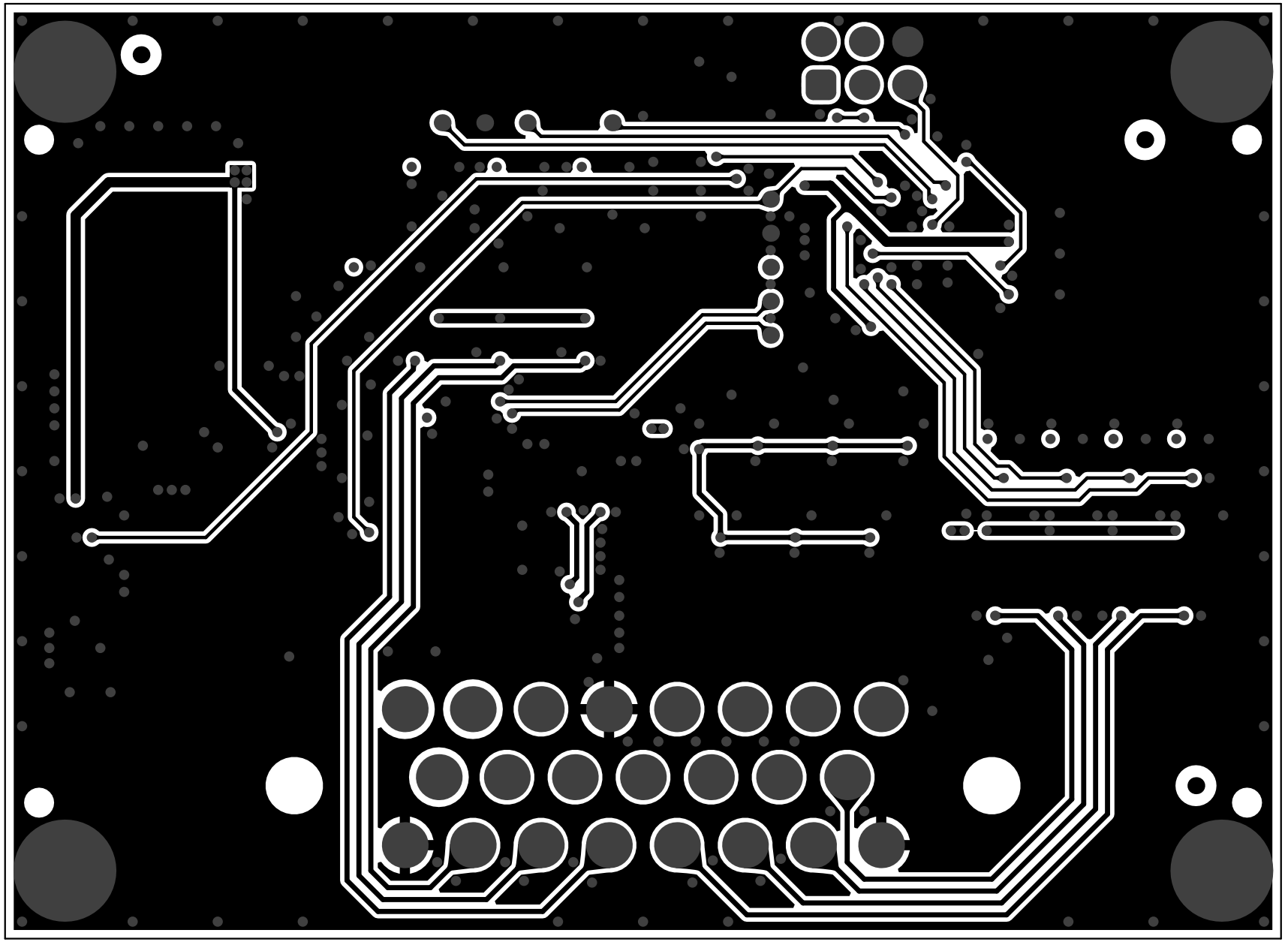
J1 PINOUT

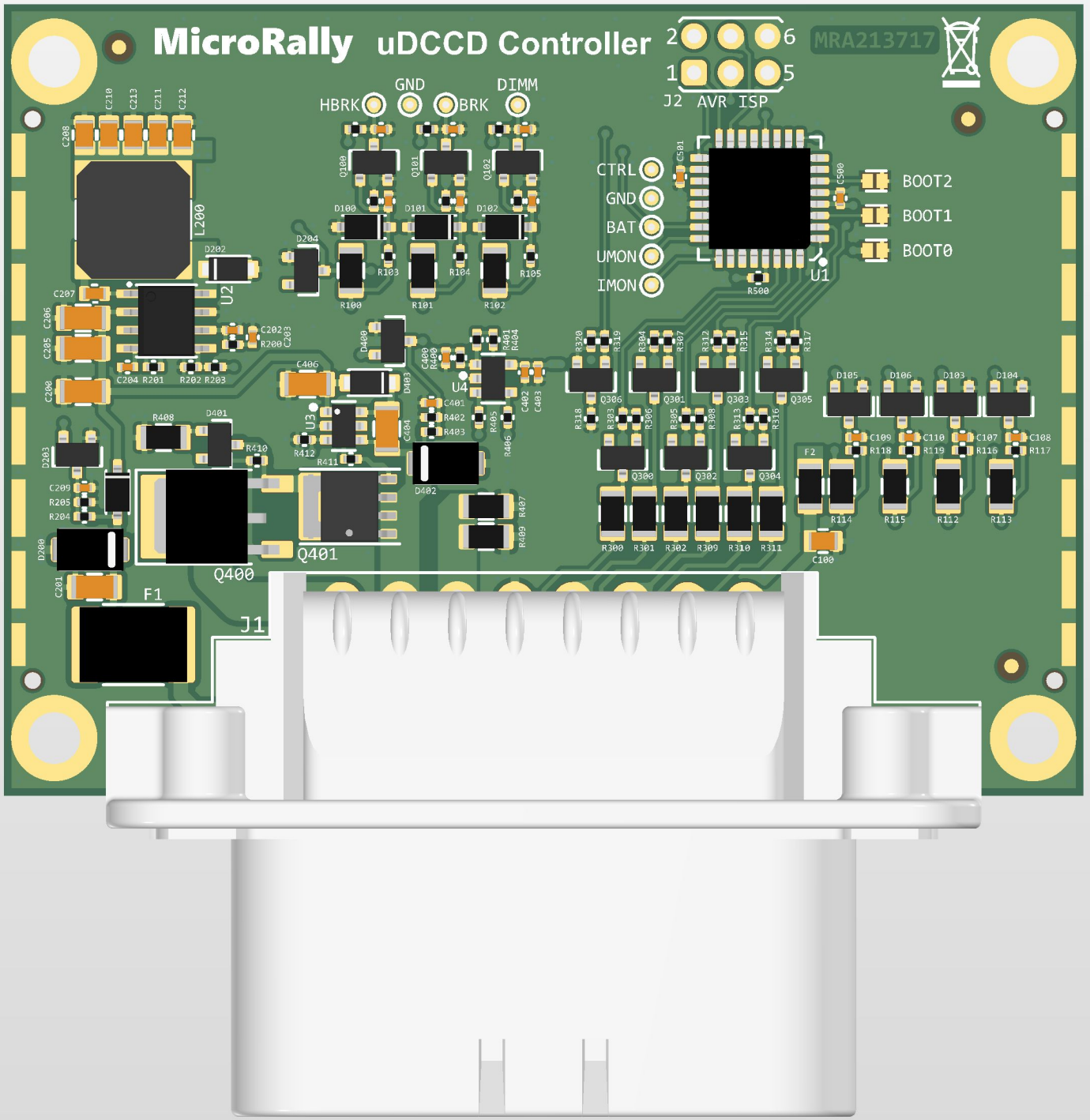



MRA213717





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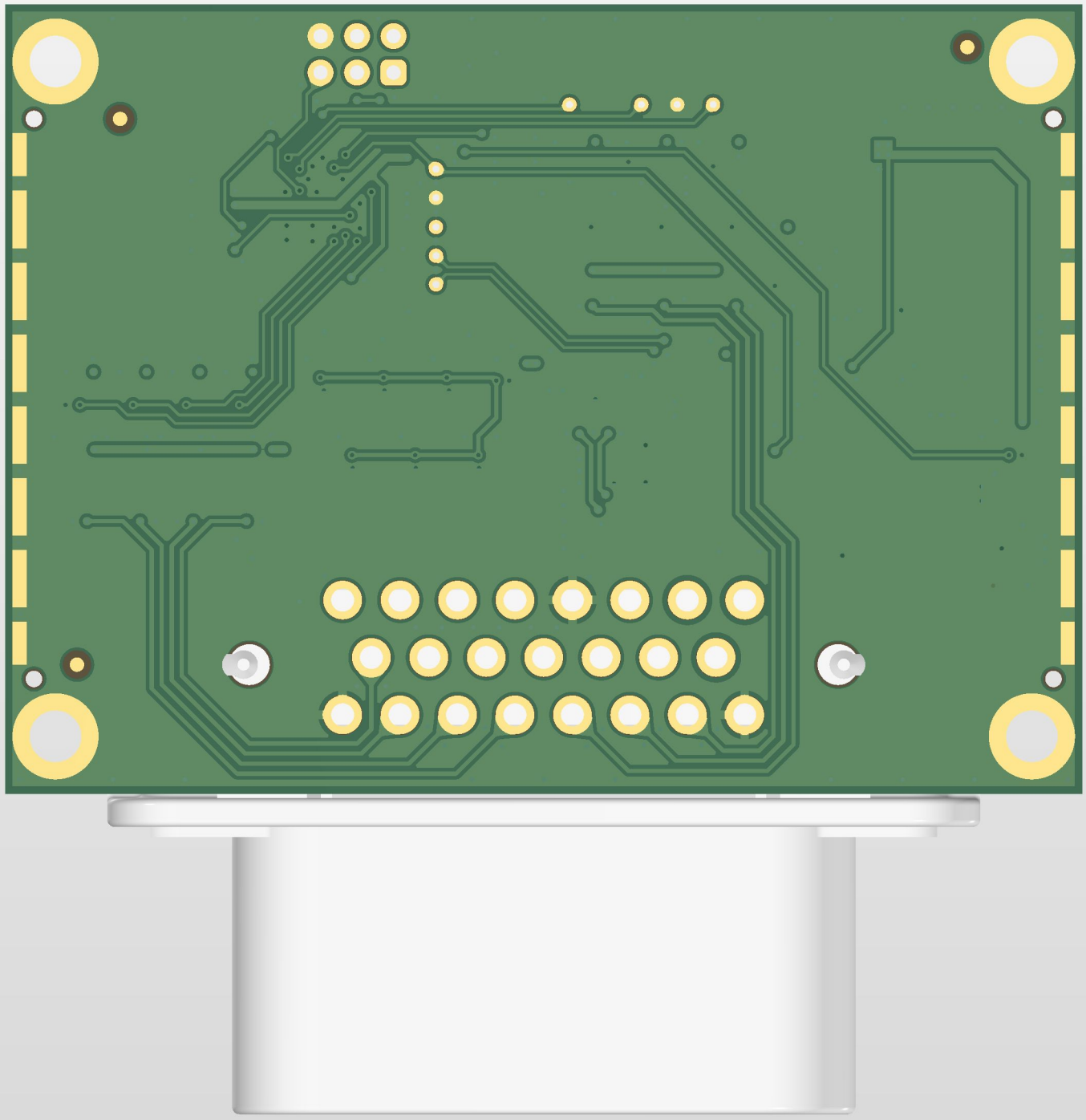

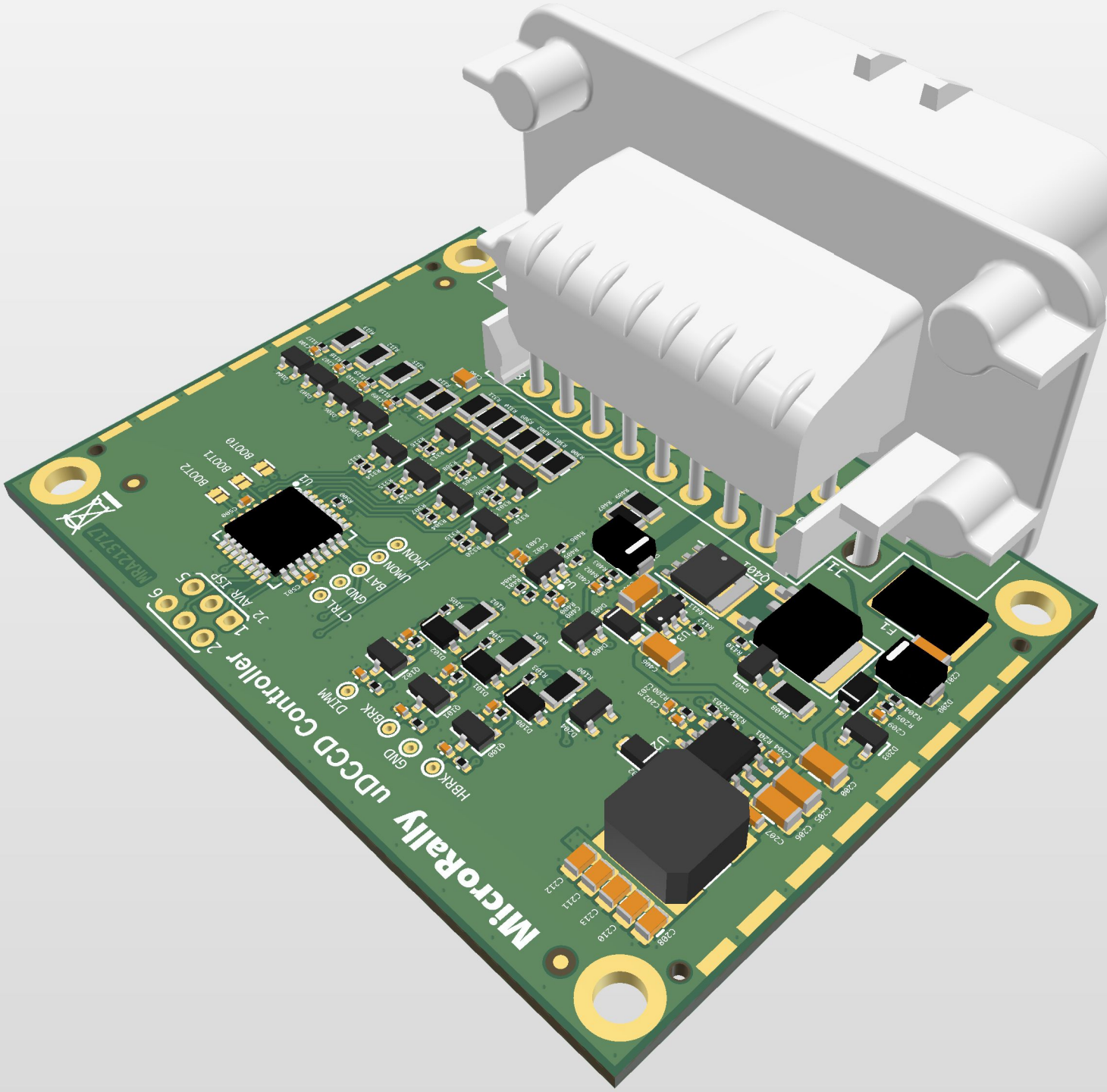
MicroRally uDCCD controller
J2 AVR ISP
1
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6
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BOOT0
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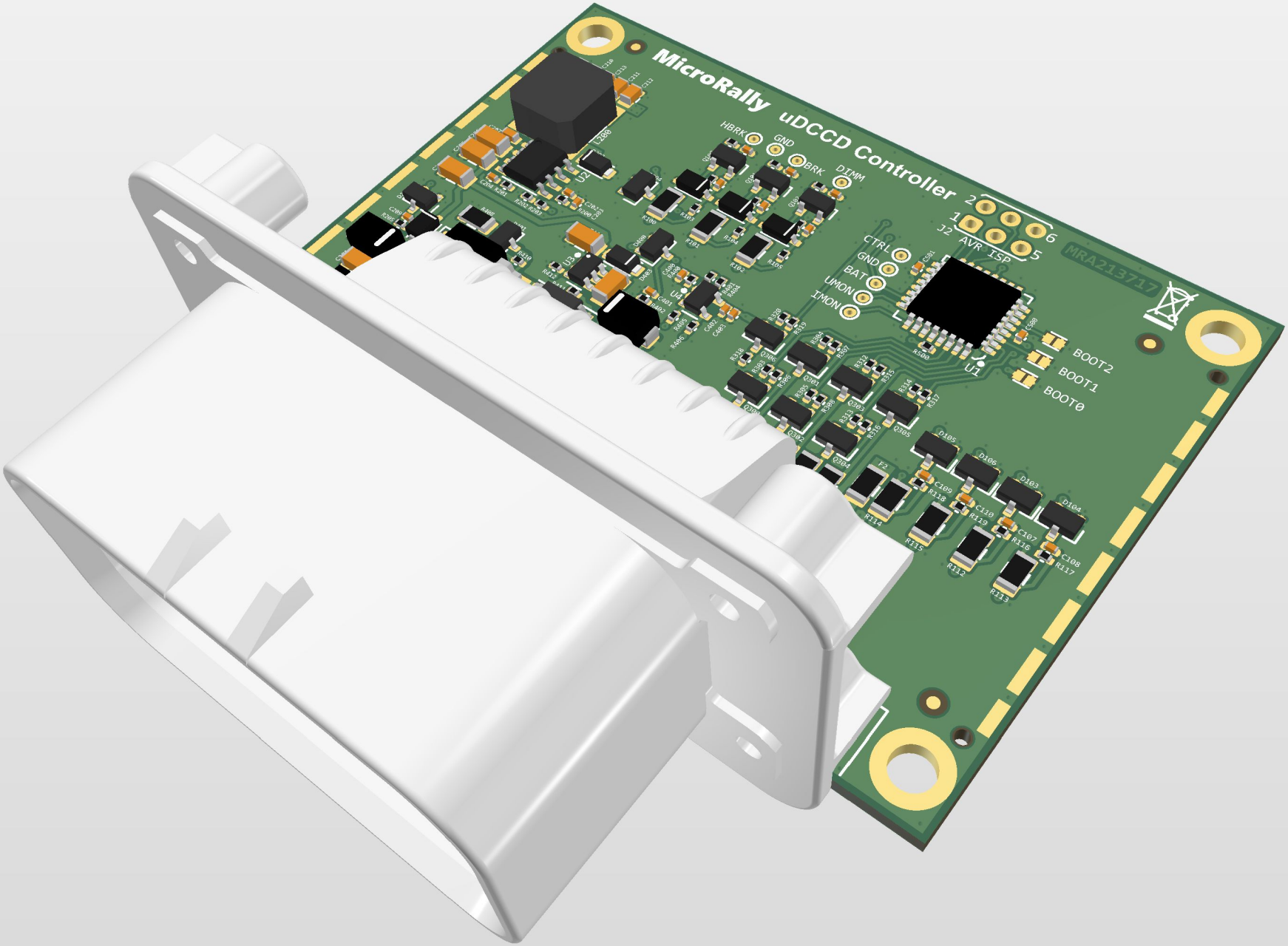
E1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